CM600HA-24A

Single

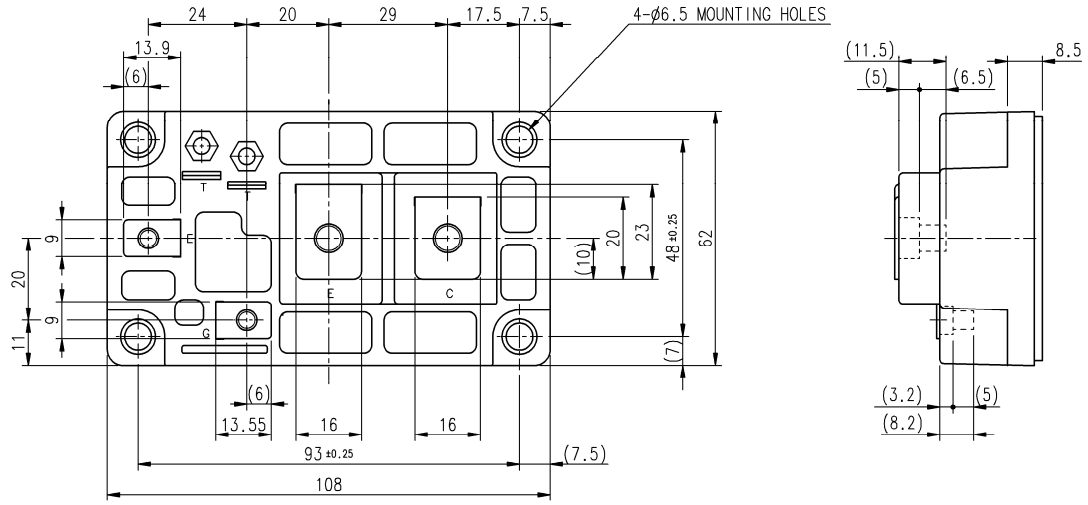
- I_C ..... 600 A
- V_{CES} ..... 1200 V
- Flat base Type
  Copper (non-plating) base plate
  No accessory (terminal screw) attach
- RoHS Directive compliant

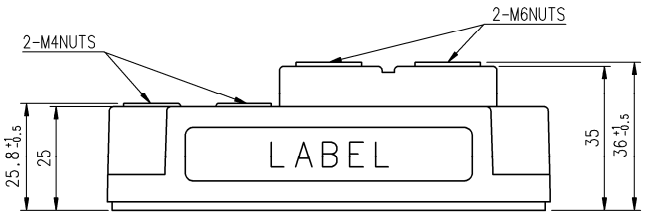
APPLICATION

AC Motor Control, Motion/Servo Control, Power supply, etc.

OUTLINE DRAWING & INTERNAL CONNECTION

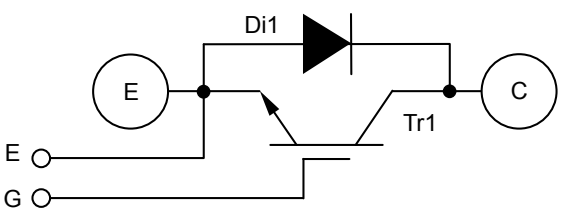
Dimension in mm





Tolerance otherwise specified	
Division of Dimension	Tolerance
0.5 to 3	±0.2
over 3 to 6	±0.3
over 6 to 30	±0.5
over 30 to 120	±0.8
over 120 to 400	±1.2

INTERNAL CONNECTION



MITSUBISHI ELECTRIC

ABSOLUTE MAXIMUM RATINGS (T_j=25 °C, unless otherwise specified)

Symbol	Item	Conditions	Rating	Unit
V_{CES}	Collector-emitter voltage	G-E short-circuited	1200	V
V_{GES}	Gate-emitter voltage	C-E short-circuited	±20	V
I_C	Collector current	DC, T_C=80 °C (Note.2)	600	A
I_{CRM}		Pulse, Repetitive (Note.3)	1200	
P_{tot}	Total power dissipation	T_C=25 °C (Note.2, 4)	3670	W
I_E (Note.1)	Emitter current (Free wheeling diode forward current)	T_C=25 °C (Note.2, 4)	600	A
I_{ERM} (Note.1)		Pulse, Repetitive (Note.3)	1200	
T_j	Junction temperature	-	-40 ~ +150	°C
T_{stg}	Storage temperature	-	-40 ~ +125	
V_{isol}	Isolation voltage	Terminals to base plate, RMS, f=60 Hz, AC 1 min	2500	V

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
M_t	Mounting torque	Main terminals M 6 screw	1.96	2.45	2.94	N·m
M_t		Auxiliary terminals M 4 screw	0.98	1.18	1.47	
M_s		Mounting to heat sink M 6 screw	1.96	2.45	2.94	
m	Weight	-	-	480	-	g
e_c	Flatness of base plate	On the centerline X, Y (Note.5)	±0	-	+100	µm

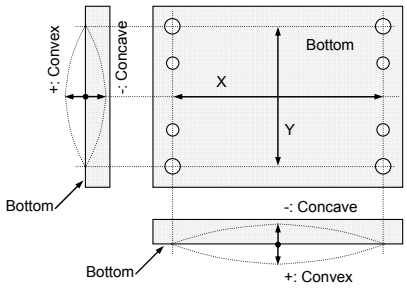
ELECTRICAL CHARACTERISTICS (T_j=25 °C, unless otherwise specified)

Symbol	Item	Conditions		Limits			Unit
				Min.	Typ.	Max.	
I_{CES}	Collector-emitter cut-off current	V_{CE}=V_{CES}, G-E short-circuited		-	-	1	mA
I_{GES}	Gate-emitter leakage current	±V_{GE}=V_{GES}, C-E short-circuited		-	-	1.5	µA
$V_{GE(th)}$	Gate-emitter threshold voltage	I_C=60 mA, V_{CE}=10 V		6	7	8	V
V_{CEsat}	Collector-emitter saturation voltage	I_C=600 A (Note.6), V_{GE}=15 V	T_j=25 °C	-	2.1	3.0	V
			T_j=125 °C	-	2.4	-	
C_{ies}	Input capacitance	V_{CE}=10 V, G-E short-circuited		-	-	105	nF
C_{oes}	Output capacitance			-	-	9.0	
C_{res}	Reverse transfer capacitance			-	-	2.0	
Q_G	Gate charge	V_{CC}=600 V, I_C=600 A, V_{GE}=15 V		-	3000	-	nC
$t_{d(on)}$	Turn-on delay time	V_{CC}=600 V, I_C=600 A, V_{GE}=±15 V, R_G=0.52 Ω, Inductive load		-	-	660	ns
t_r	Rise time			-	-	190	
$t_{d(off)}$	Turn-off delay time			-	-	700	
t_f	Fall time			-	-	350	
V_{EC} (Note.1)	Emitter-collector voltage	I_E=600 A (Note.6), G-E short-circuited		-	3.0	3.8	V
t_{rr} (Note.1)	Reverse recovery time	V_{CC}=600 V, I_E=600 A, V_{GE}=±15 V, R_G=0.52 Ω, Inductive load		-	-	250	ns
Q_{rr} (Note.1)	Reverse recovery charge			-	19	-	µC
E_{on}	Turn-on switching energy per pulse	V_{CC}=600 V, I_C=I_E=600 A, V_{GE}=±15 V, R_G=0.52 Ω, T_j=125 °C, Inductive load		-	100	-	mJ
E_{off}	Turn-off switching energy per pulse			-	66	-	
E_{rr} (Note.1)	Reverse recovery energy per pulse			-	29.5	-	
r_g	Internal gate resistance	T_C=25 °C		-	1.0	-	Ω
R_G	External gate resistance	-		0.52	-	7.8	Ω

THERMAL RESISTANCE CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
$R_{th(j-c)Q}$	Thermal resistance (Note.2)	Junction to case, IGBT part	-	-	34	K/kW
$R_{th(j-c)D}$		Junction to case, FWDi part	-	-	53	K/kW
$R_{th(c-s)}$	Contact thermal resistance (Note.2)	Case to heat sink, Thermal grease applied (Note.7)	-	20	-	K/kW

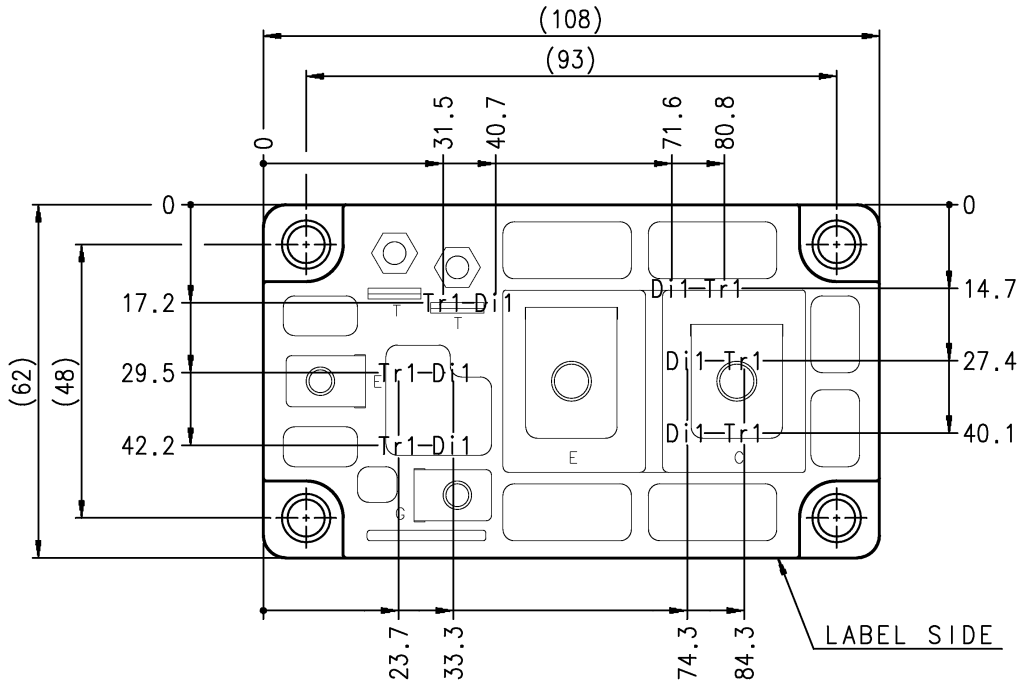
Note.1: Represent ratings and characteristics of the anti-parallel, emitter-collector free wheeling diode (FWDi).
Note.2: Case temperature (T_C) and heat sink temperature (T_s) are defined on the each surface of base plate and heat sink just under the chips. (Refer to the figure of chip location)
The heat sink thermal resistance {$R_{th(s-a)}$} should measure just under the chips.
Note.3: Pulse width and repetition rate should be such that the device junction temperature (T_j) dose not exceed T_{jmax} rating.
Note.4: Junction temperature (T_j) should not increase beyond T_{jmax} rating.
Note.5: Base plate flatness measurement point is as in the following figure.



Note.6: Pulse width and repetition rate should be such as to cause negligible temperature rise.
(Refer to the figure of test circuit)
Note.7: Typical value is measured by using thermally conductive grease of λ=0.9 W/(m·K).

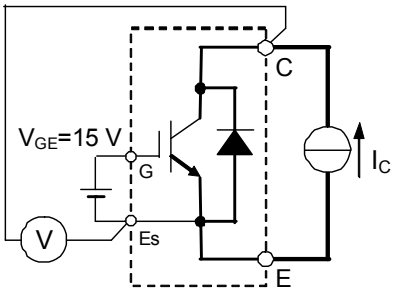
CHIP LOCATION (Top view)

Dimension in mm, tolerance: ±1 mm

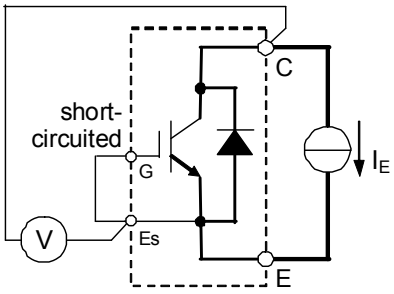


Tr1: IGBT, Di1: FWDi. Each mark points the center position of each chip.

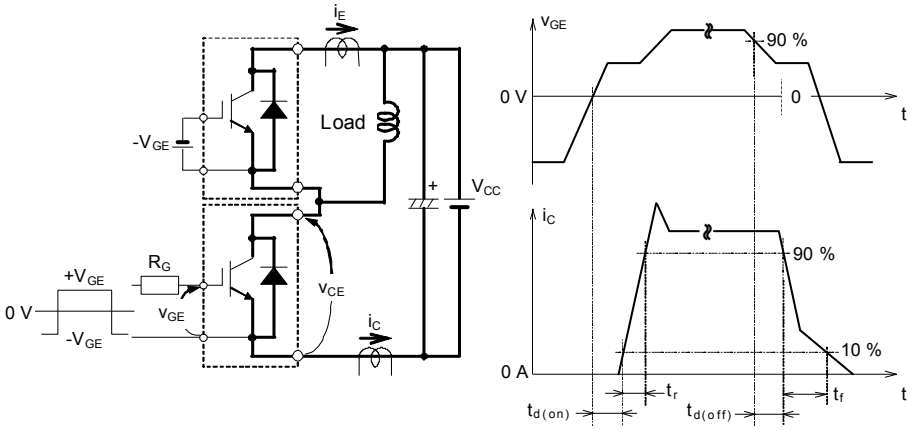
TEST CIRCUIT AND WAVEFORMS



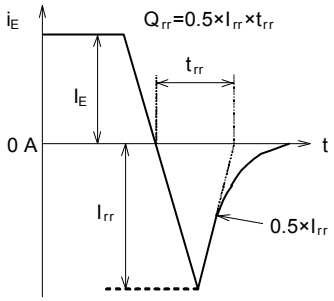
V_{CEsat} test circuit



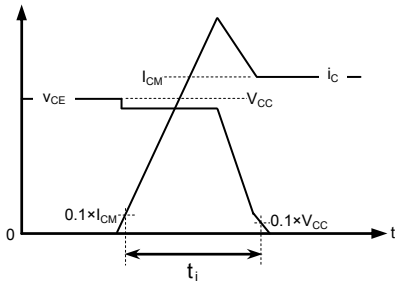
V_{EC} test circuit



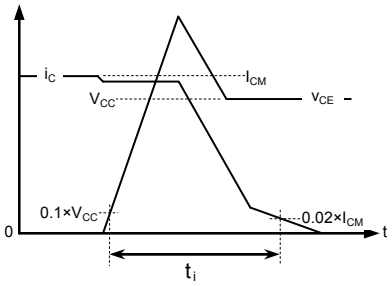
Switching characteristics test circuit and waveforms



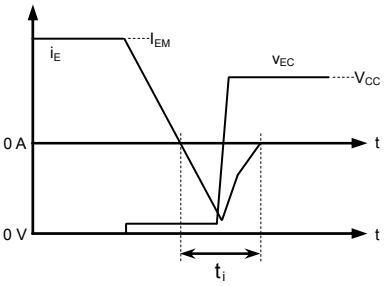
t_{rr}, Q_{rr} test waveform



IGBT Turn-on switching energy



IGBT Turn-off switching energy



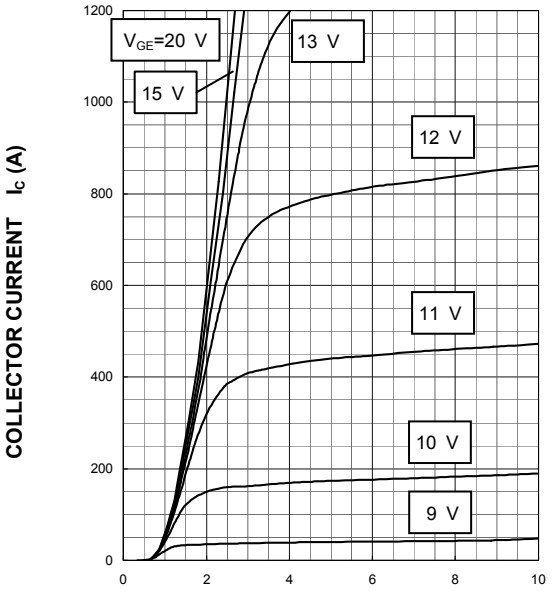
FWDi Reverse recovery energy

Turn-on, Turn-off switching and Reverse recovery energy test waveforms (integral range)

PERFORMANCE CURVES

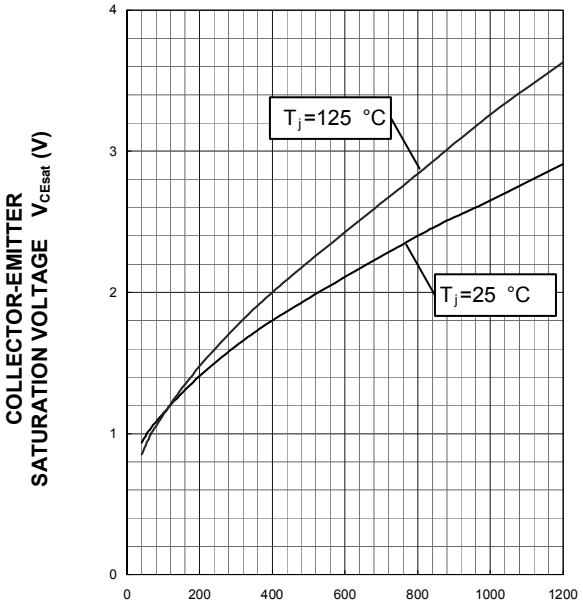
OUTPUT CHARACTERISTICS (TYPICAL)

T_j=25 °C



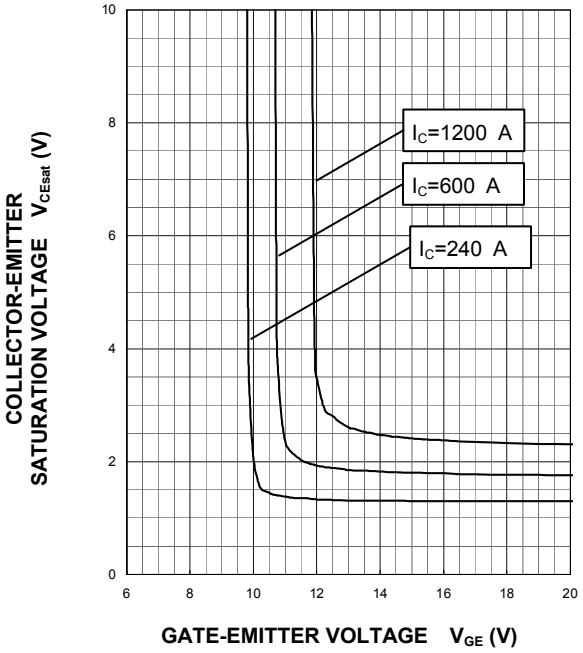
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)

V_{GE}=15 V



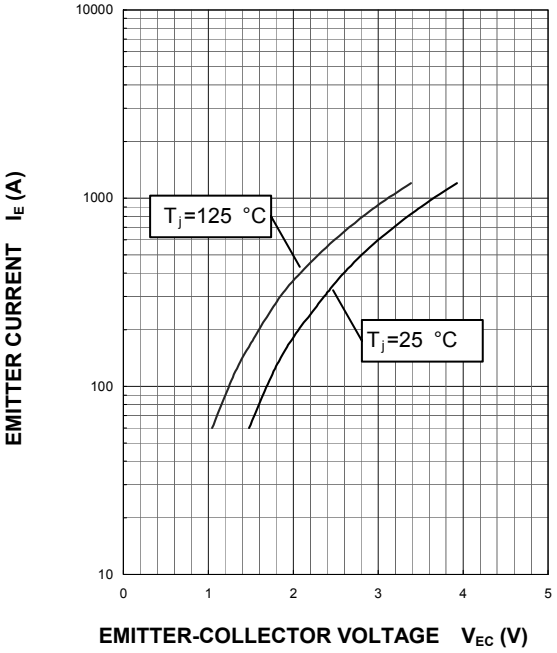
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)

T_j=25 °C

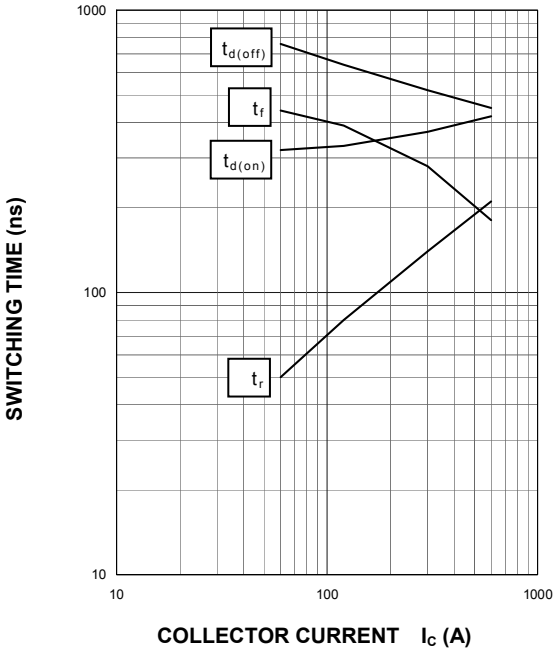


FREE WHEELING DIODE FORWARD CHARACTERISTICS (TYPICAL)

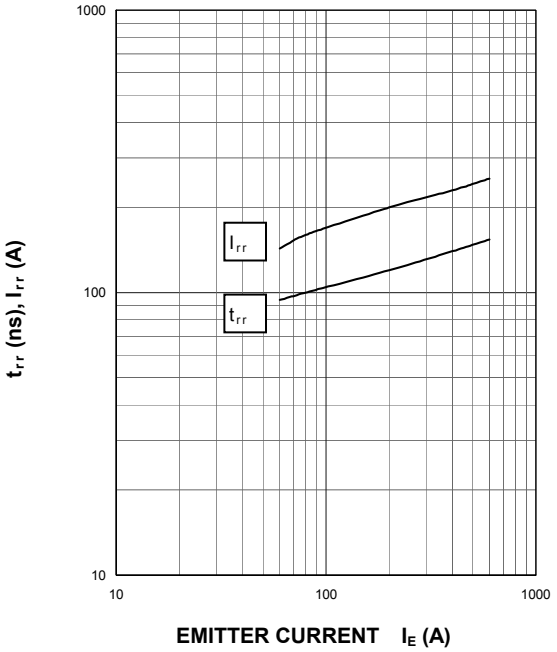
G-E short-circuited



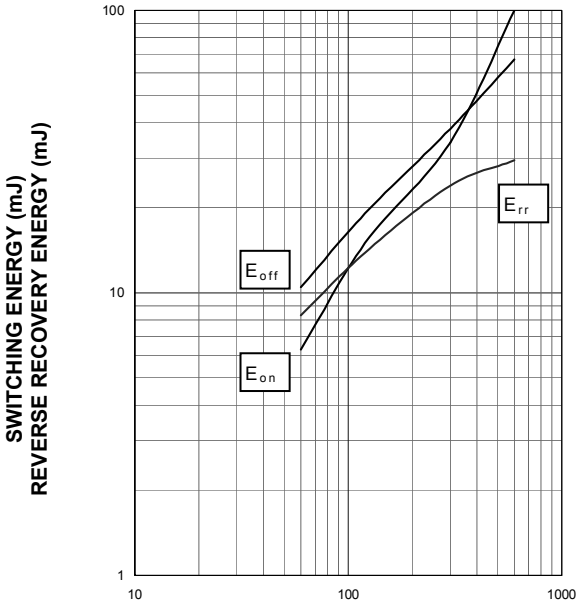
HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)
V_{CC}=600 V, V_{GE}=±15 V, R_G=0.52 Ω, T_j=125 °C
INDUCTIVE LOAD



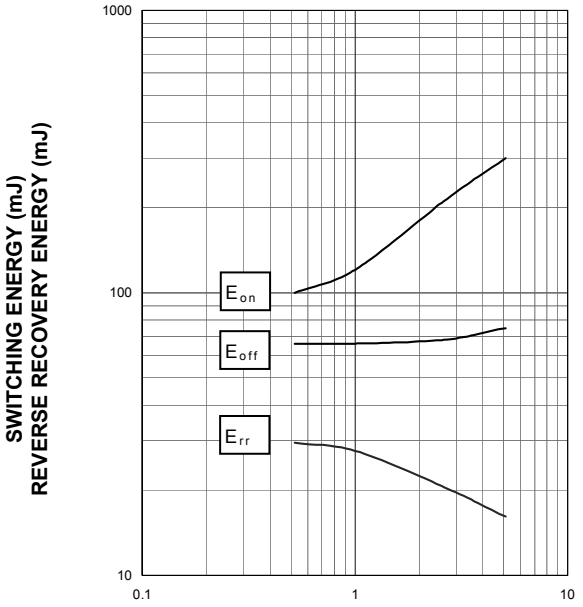
FREE WHEELING DIODE
REVERSE RECOVERY CHARACTERISTICS
(TYPICAL)
V_{CC}=600 V, V_{GE}=±15 V, R_G=0.52 Ω, T_j=125 °C
INDUCTIVE LOAD



HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)
V_{CC}=600 V, V_{GE}=±15 V, R_G=0.52 Ω, T_j=125 °C
INDUCTIVE LOAD, PER PULSE

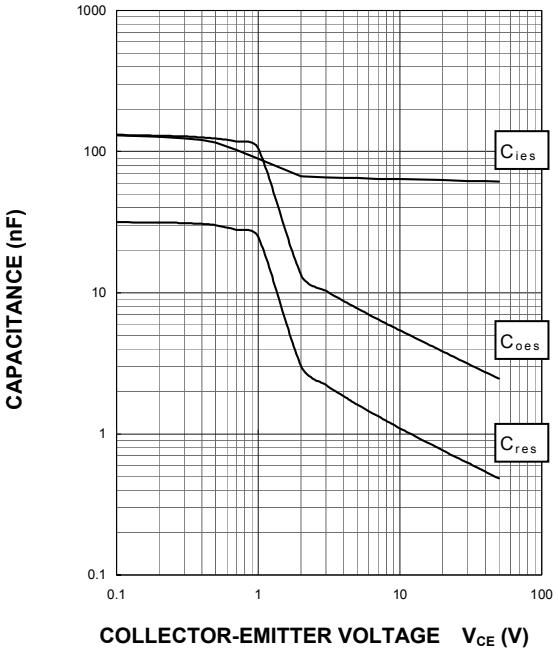


HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)
V_{CC}=600 V, I_C/I_E=600 A, V_{GE}=±15 V, T_j=125 °C
INDUCTIVE LOAD, PER PULSE



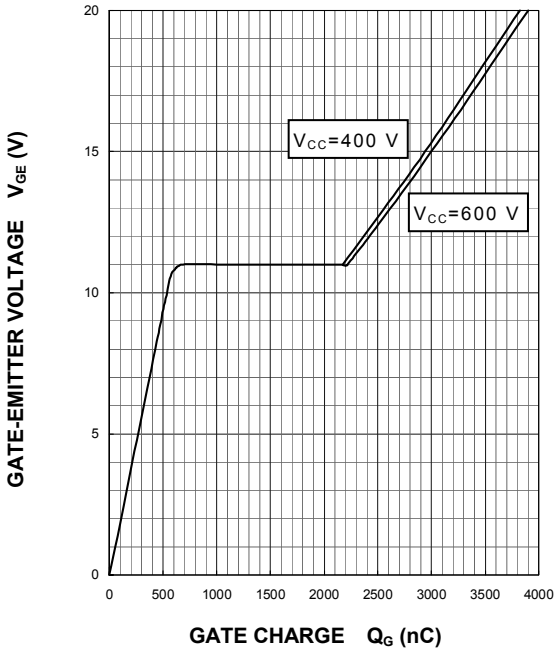
CAPACITANCE CHARACTERISTICS (TYPICAL)

G-E short-circuited, T_j=25 °C



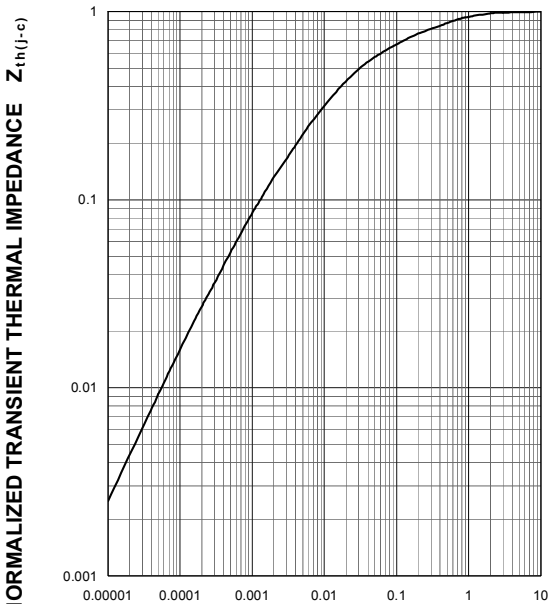
GATE CHARGE CHARACTERISTICS (TYPICAL)

I_C=600 A, T_j=25 °C



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (MAXIMUM)

Single pulse, T_C=25°C



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